

### **Amendments to the Claims:**

Claims 1 and 19 have been amended and Claims 8, 12-18 and 21-36 have been cancelled without prejudice or disclaimer of that which is defined thereby (as those claims have been allowed in the '763 application, from which this application continues), in the following Claims Listing that is submitted to replace all prior claims in the application. New Claim 39 is also submitted hereby.

### **CLAIMS LISTING:**

1. (Currently Amended) A thermal interface wafer for facilitating heat transfer from an electronic component to a heat sink when interposed therebetween, said wafer comprising at least one linear ~~planar~~ substrate having first and second surfaces with edges, said substrate having at least one layer of conformable, heat-conductive material formed upon a respective surface thereof, said heat-conductive material being formulated to enhance the heat transfer from said electronic component to said heat sink, wherein the wafer is formed from a cross-section having a shape selected from the group consisting of generally rectangular, generally circular, and generally square and said substrate is disposed to assume a substantially perpendicular orientation relative to the electronic component whereby the edges of ~~the wafer~~ said substrate contact the electronic component and the heat sink.

2. (Original) The thermal interface wafer of Claim 1 wherein said vertically-oriented planar substrate comprises a metallic layer.

3. (Original) The thermal interface wafer of Claim 2 wherein said metallic layer is selected from the group consisting of copper, gold, silver and aluminum.

4. (Original) The thermal interface wafer of Claim 1 wherein said planar substrate has a width no greater than about 0.2 inches.

5. (Original) The thermal interface wafer of Claim 1 when said planar substrate has a width no greater than about 0.01 inches.

6. (Original) The thermal interface wafer of Claim 1 wherein said planar substrate has a width from about 0.005 to 0.01 inches.

7. (Original) The thermal interface wafer of Claim 1 wherein said substrate with conformable, heat-conducting material is formed as a coil.

8. (Cancelled)

9. (Original) The thermal interface wafer of Claim 1 wherein said wafer is comprised of a multiplicity of vertically oriented planar substrates, each respective one of said substrates having said conformable, heat-conducting material formed upon a respective side thereof.

10. (Original) The thermal interface wafer of Claim 9 wherein said wafer is comprised from a multiplicity of planar substrates with dedicated layers of conformable, heat-conducting material formed thereon.

11. (Original) The thermal interface wafer of Claim 9 wherein said substrates with heat-conductive material formed thereon are arranged and generally parallel in relation to one another and compressibly bonded to one another.

12. (Cancelled)

13. (Currently Amended) A thermal interface for facilitating heat transfer from an electronic component to a heat sink comprising at least one elongate planar strip substrate having first and second sides with at least one layer of conformable, heat-conducting material formed upon a respective one of said sides, said at least one strip with at least one layer of

heat-conducting material formed thereon being formed as a cross-sectional portion of an outwardly-spiraling coil having a shape selected from the group consisting of generally rectangular and generally square to define a wafer interposable between said electronic component and said heat sink.

14. (Original) The thermal interface of Claim 13 wherein said substrate comprises a metal foil selected from the group consisting of copper, gold, silver and aluminum.

15. (Cancelled)

16. (Cancelled)

17. (Cancelled)

18. (Cancelled)

19. (Currently Amended) A thermal interface for facilitating heat transfer from an electronic component to a heat sink comprising a multiplicity of elongate, vertically-oriented substrates, each respective substrate having at least one layer of conformable, heat-conducting material formed thereon, said multiplicity of elongate strips being formed in generally parallel relation to one another to define a wafer interposable between said electronic component and said heat sink, wherein said thermal interface is formed from a cross-section having a shape selected from the group consisting of generally rectangular, generally circular and generally square.

20. (Original) The thermal interface of Claim 19 wherein said substrates are comprised of a metal foil selected from the group consisting of copper, gold, silver and aluminum.

21. (Cancelled)

22. (Cancelled)

23. (Cancelled)
24. (Cancelled)
25. (Cancelled)
26. (Cancelled)
27. (Cancelled)
28. (Cancelled)
29. (Cancelled)
30. (Cancelled)
31. (Cancelled)
32. (Cancelled)
33. (Cancelled)
34. (Cancelled)
35. (Cancelled)
36. (Cancelled)
37. (New) The thermal interface of Claim 1 wherein said heat-conductive material melts at a temperature from between approximately 51° C and 60° C.
38. (New) The thermal interface of Claim 13 wherein said heat-conductive material melts at a temperature from between approximately 51° C and 60° C.
39. (New) The thermal interface of Claim 19 wherein said heat-conductive material melts at a temperature from between approximately 51° C and 60° C.